



HSEC8-149-01-L-DV-A



(0,80 mm) .0315"

HSEC8-DV SERIES

VERTICAL EDGE RATE™ CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DV

Insulator Material:

Black Liquid Crystal Polymer

Contact: BeCu

Plating:

Au or Sn over 50µ" (1,27 µm) Ni

Current Rating:

1.9A per contact

@ 30°C Temperature Rise

(See website for details)

Operating Temp:

-55°C to +125°C

Card Insertion Depth:

(3,15 mm) .125" nominal

RoHS Compliant: Yes

Processing:

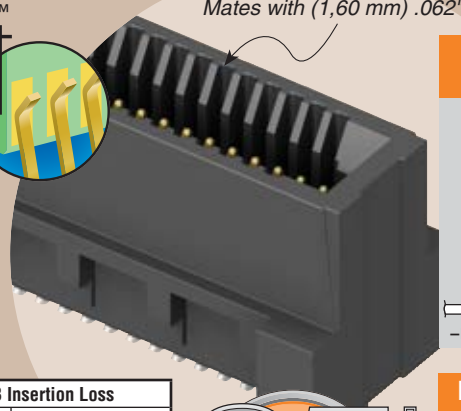
Lead-Free Solderable: Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (10-60)

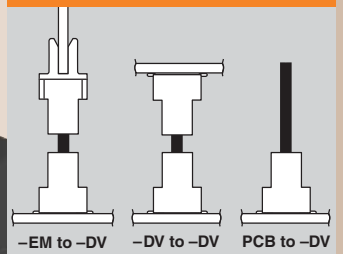


Mates with:
1,60 mm thick cards,
ECDP, HSC8

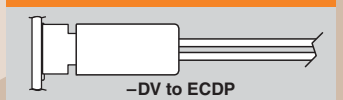


Mates with (1,60 mm) .062"

BOARD-TO-BOARD APPLICATIONS



HIGH SPEED CABLE APPLICATIONS



HSEC8	Rated @ 3dB Insertion Loss	
	with PCB effects*	w/o PCB effects**
7,98 mm Stack Height		
Single-Ended Signaling	8 GHz / 16 Gbps	9 GHz / 18 Gbps
Differential Pair Signaling	10.5 GHz / 21 Gbps	14 GHz / 28 Gbps

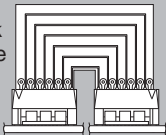
*Performance data includes effects of a non-optimized PCB.
**Test board losses de-embedded from performance data.

Complete test data available at www.samtec.com?HSEC8-DV or contact sig@samtec.com



STANDARD & CUSTOM CARDS AVAILABLE

- Standard high speed interface cards for 19 mm, 25 mm & 30 mm mated heights, single-ended & differential applications. See HSC8 Series.
- (2,36 mm) .093" thick card
- Custom cards for low-cost stack height customization
- Samtec supplied card layout/artwork to make your own cards
- Specialty card shapes



APPLICATION SPECIFIC OPTION

Guide rails and pass-through options. Call Samtec.

Note: While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Note: Some lengths, styles and options are non-standard, non-returnable.



09, 10, 13, 20, 25, 30,
37, 40, 49, 50, 60
(13, 25, 49 only available with -L or -L2 option;
09 only available with -L2 option;
37 only available with -L option)

-01
= (1,60 mm) .062" thick card

-L
= 10µ" (0,25 µm)
Gold on contact,
Matte Tin on tail

Note: Other Gold plating options available. Contact Samtec.

-K
= (5,50 mm) .217" DIA
Polyimide Film
Pick & Place Pad

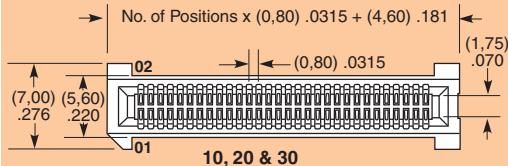
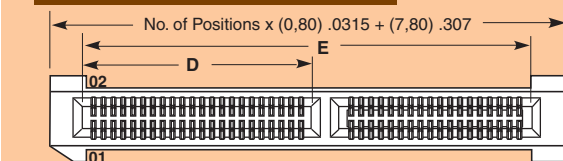
-BL
= Board Locks
(40, 50, 60 only)
(Other sizes available. Contact Samtec.)

-L
= Latching Option
(13, 25, 37, 49 only)

-L2
= ECDP Latching
09, 13, 25, 49 only
(For use with ECDP)

-WT
= Weld tab

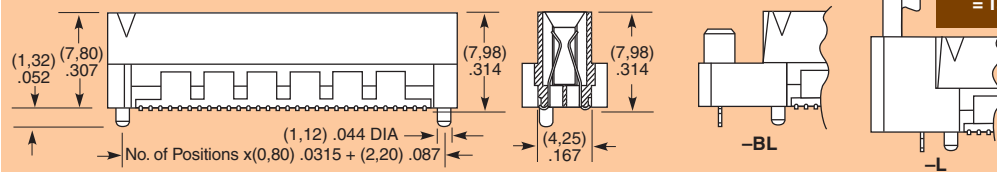
-TR
= Tape & Reel



POSITIONS PER ROW	D	E
09	(4,50) .177	(11,80) .458
13*	(6,10) .240	(15,00) .591
25*	(6,10) .240	(24,60) .969
37	(18,10) .713	(34,20) 1.346
40	(18,90) .744	(36,60) 1.441
49*	(22,90) .902	(43,80) 1.724
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071

Positions where no dimensions are given do not have keying feature.
*Mates with ECDP Series.

CABLE CONNECTOR	HSEC8
ECDP-04	HSEC8-109-L2
ECDP-08	HSEC8-113-L2
ECDP-16	HSEC8-125-L2
ECDP-32	HSEC8-149-L2



Due to technical progress, all designs, specifications and components are subject to change without notice.

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